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Semiconductor device and its manufacturing method

ABSTRACT OF THE DISCLOSURE:

An effectively chip size semiconductor package comprises: a square semiconductor chip wherein plural connection terminals are arranged in a peripheral part; an elastic body disposed on a main surface of the semiconductor chip leaving the plural connection terminals exposed; an insulating tape formed on the elastic body and having openings in areas where the connection terminals are situated; plural leads formed on the top surface of the insulating tape, one end of each lead being connected to the connection terminals and the other end being disposed on the elastic body; plural bump electrodes formed on the other ends of the plural leads; and a resin body for sealing the connection terminals of the semiconductor chip and one end of each of the leads, wherein the insulating tape protrudes beyond the semiconductor chip near the peripheral part where the plural connection terminals are arranged, and wherein the shape of the resin body is restricted by the protruding part of the insulating tape.

The elastic body comprises a porous material, has a substantially identical shape to that of the insulating tape, and is formed so that one of its lateral surfaces is exposed to the outside environment.

Figure 1

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